

## Material Composition Declaration

© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard  
<http://www.ipc.org/IPC-175x>

Form Type\*  
Distribute

**Declaration Class\***  
**Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information**

### Supplier Information

<b>Company Name *</b> Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	<b>Response Date*</b> Sat, May 26, 2012 01:51 AM
<b>Contact Name *</b> David Lancaster	Title - Contact Product Ecology	<b>Phone - Contact *</b> 801-562-7455	<b>Email - Contact *</b> david.lancaster@fairchildsemi.com
<b>Authorized Representative *</b> David Lancaster	Title - Representative Product Ecology	<b>Phone - Representative *</b> 801-562-7455	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mf Item Number	Mf Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
1V5KE200CA	1V5KE200CA	DO-201AE			SUBCONTRACTOR	1.132	g	Each

### Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	Other	Not Applicable	C	seconds	Not Applicable

\* Required Field

<b>RoHS Material Composition Declaration</b>	<b>Declaration Type * Custom</b>
--	----------------------------------

<b>RoHS Directive 2002/95/EC</b>	<b>RoHS Definition:</b> Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium
----------------------------------	---

Providing for limitations below, we certify that the Fairchild Semiconductor product(s) list in this document are compliant to directive 2002/95/EC of the European Parliament and of the council on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS directive). Specifically, this product(s) does not contain the substances in the RoHS definition above in concentrations greater than the maximum limit value(a).

Fairchild has implemented procedures to ensure our products and the materials in our products conform to regulatory requirements worldwide. Fairchild Semiconductor certifies that the information provided in this document is correct as of the date indicated on this document. However, not all materials in Fairchild's products may have been independently verified or tested with regard to substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

(a) Maximum limit does not apply to applications for which exemptions have been granted by the RoHS directive. Fairchild product may utilize exemption 5 and 7a.

<b>RoHS Declaration *</b>	<b>4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions</b>	<b>Supplier Acceptance * Accepted</b>
---------------------------	--	---------------------------------------

**Exemptions:** If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2006/690/EC

7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead).

<b>Declaration Signature</b>
------------------------------

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER
--------------------	--

**Homogeneous Material Composition Declaration for Electronic Products**

Item/SubItem Name DO-201AE

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
CSS Wire	Other Ferrous alloys, non-stainless steels	510.000	Supplier		Carbon	2.550	7440-44-0	2253
			Supplier		Copper	179.000	7440-50-8	158153
			Supplier		Iron	327.000	7439-89-6	288916
			Supplier		Manganese	1.020	7439-96-5	901
			Supplier		Phosphorus	0.255	7723-14-0	225
			Supplier		Sulfur	0.255	7704-34-9	225
Chip	Other inorganic materials	3.200	Supplier		Silicon	3.200	7440-21-3	2827
Die Attach	Other Nonferrous metals & alloys	2.220	A	Lead/Lead Compounds	Lead	2.050	7439-92-1	1811
			Supplier		Silver	0.056	7440-22-4	49
			Supplier		Tin	0.111	7440-31-5	98
Dumet Wire	Other Ferrous alloys, non-stainless steels	305.000	Supplier		Cobalt	1.530	7440-48-4	1352
			Supplier		Iron	172.000	7439-89-6	151968
			Supplier		Manganese	2.440	7439-96-5	2156
			B	Nickel (external applications only)	Nickel	128.000	7440-02-0	113092
			Supplier		Silicon	0.916	7440-21-3	809
Encapsulation	Thermoplastics	303.675	B	Antimony/Antimony Compounds	Antimony Trioxide	6.384	1309-64-4	5640
			B	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	5.460	6386-73-8	4824
			Supplier		Epoxy Resin	75.900	29690-82-2	67060
			Supplier		Silica, vitreous	215.931	60676-86-0	190783
Plating	Other Nonferrous metals & alloys	7.760	Supplier		Tin	7.760	7440-31-5	6856